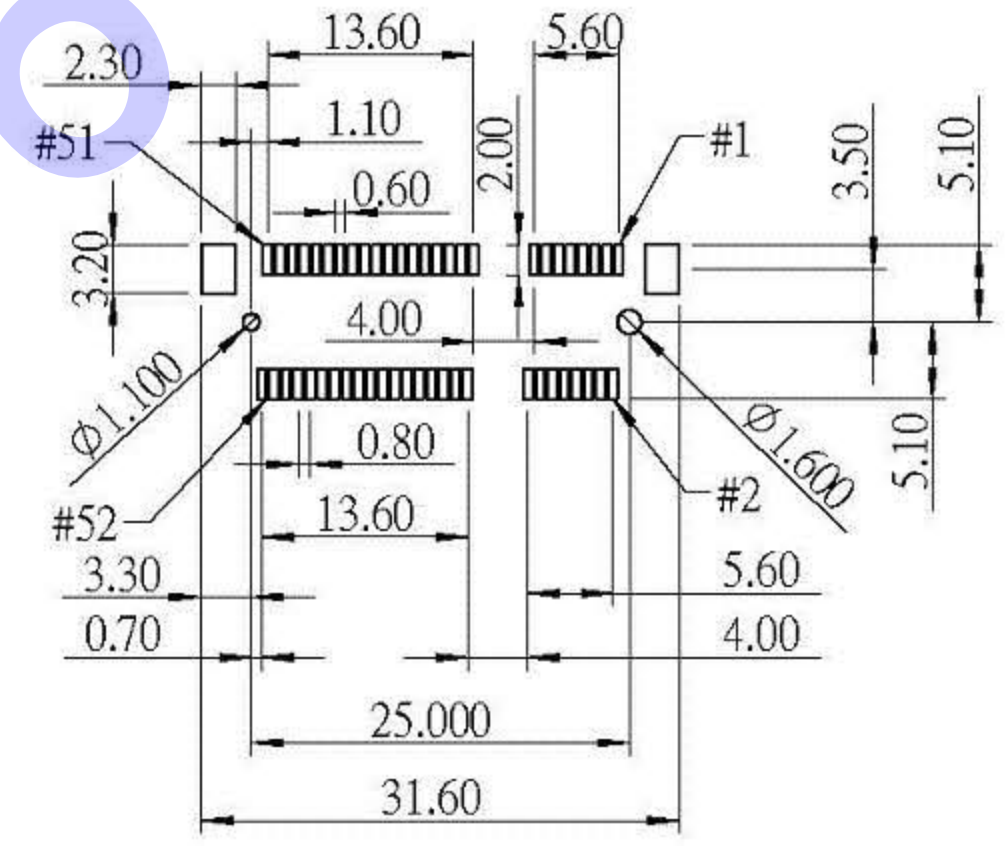
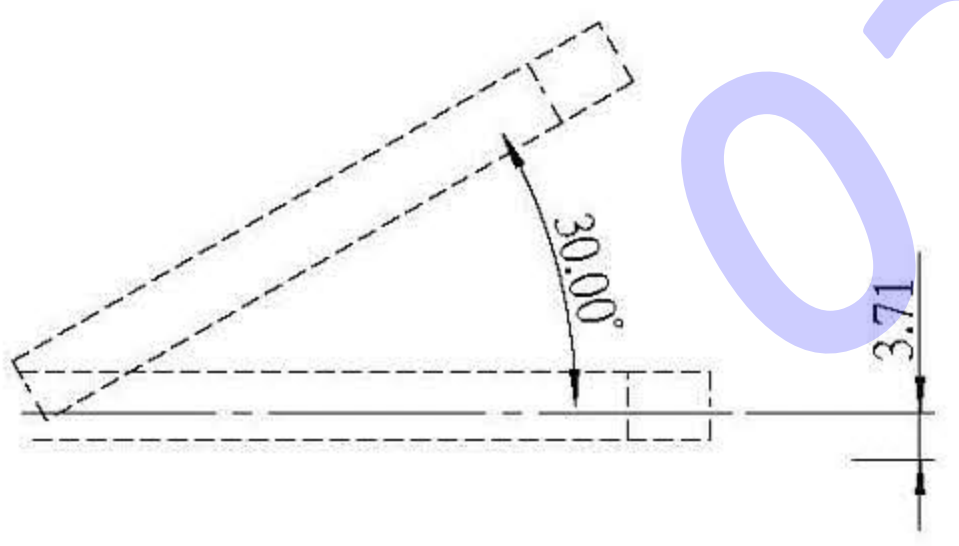
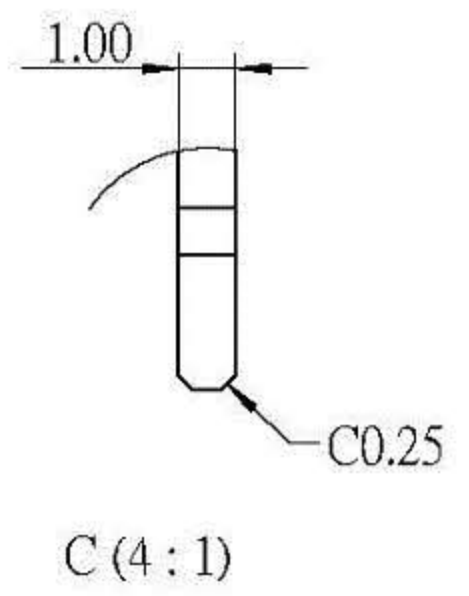
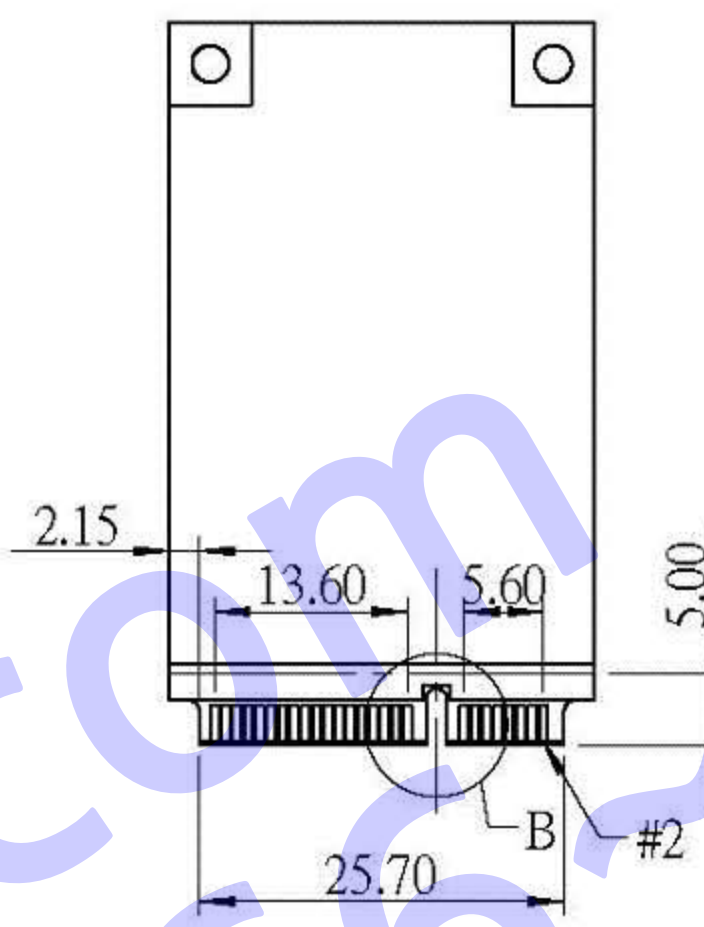
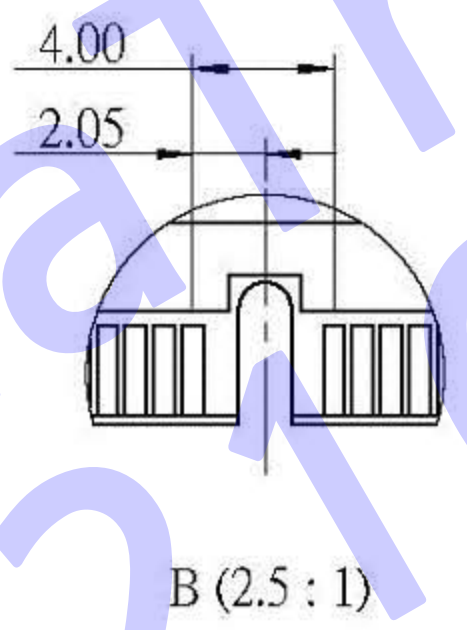
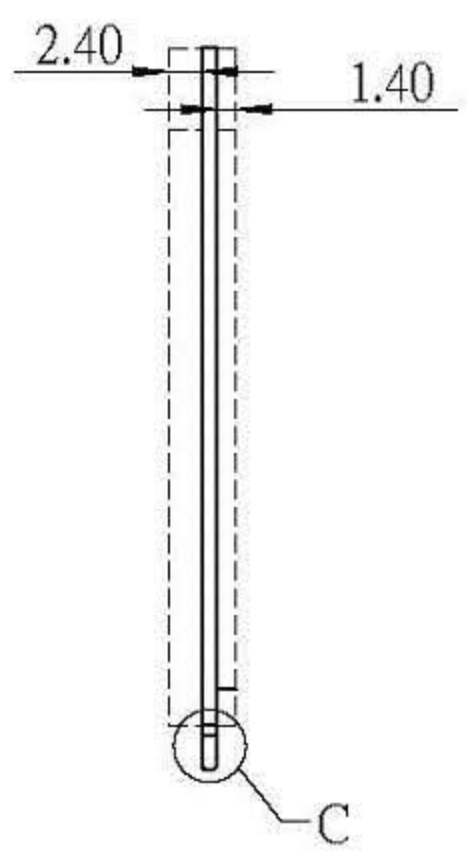
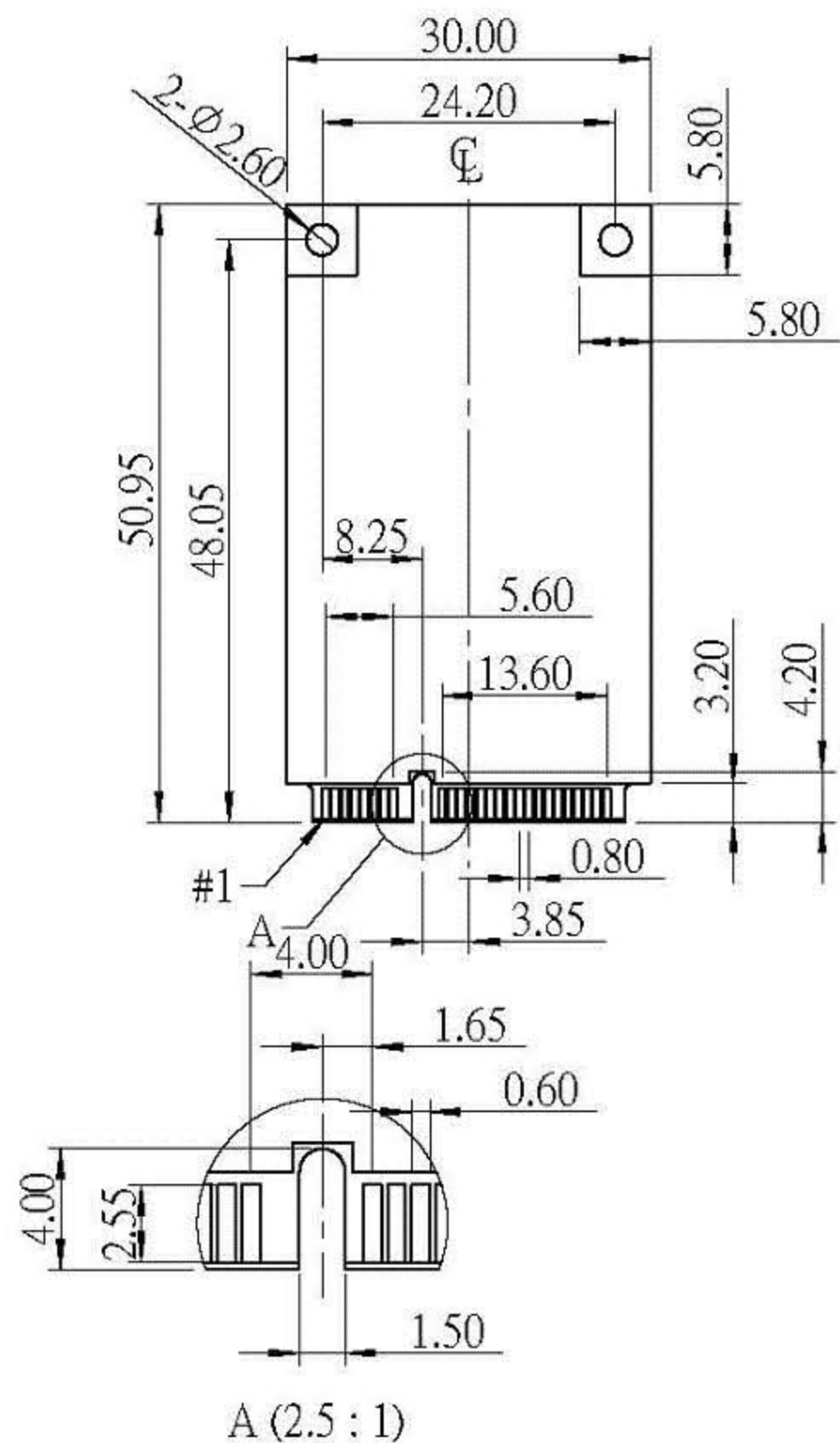


NOTE:  
 1. SOLDER TAIL TO BE WITHIN 0.05 UPWARD AND 0.2 DOWNWARD FROM Z-DATUM PLACE, AND COPLANALITY OF SOLDER TAILS TO BE WITHIN 0.10 MEASUREMENT POINT IS SOLDER TAIL TIP.  
 2. ACCORDING HSF CONCRRAFT LEVEL I  
 3. MATERIAL:  
 BASE: THERMOPLASTIC LCP, UL 94V-0, BLACK COLOR  
 TERMINAL: COPPY ALLOY  
 4. FINISH:  
 TERMINAL: GOLD FLASH PLATING ON CONTACT AREA, GOLD FLASH ON SOLDER TAIL, Ni 50μ" MIN UNDERPLATING.  
 5. INSPECTION SYMBOL:  
 ● : MANUFACTURER INSPECTION  
 ◆ : Q.C INSPECTION



PCB LAYOUT

TOLERANCE		HDC 有限公司		TITLE: MINI PCI 52P			
LINEAR	ANGLES			PART NO. GMEM-MINI PCI 52P			
X ± 0.50	X° ± 2.0°	APPD:		DRWN: Rocky		DWG NO.	
.X ± 0.30	.X° ± 1.0°					UNITS	SCALE
.XX ± 0.20	.XX° ±	CHKD:	DATE: 2012-8-22	MM	1:1	1 OF 2	A/0
.XXX ± 0.10	.XXX° ±						



TOLERANCE		HDC 有限公司		TITLE: MINI PCI 52P			
LINEAR	ANGLES			PART NO. GMEM-MINI PCI 52P			
X ± 0.50	X° ± 2.0°	APPD:		DRWN: Rocky		DWG NO.	
.X ± 0.30	.X° ± 1.0°					UNITS	SCALE
.XX ± 0.20	.XX° ±	CHKD:	DATE: 2012-8-22	MM	1:1	1 OF 2	A/0
.XXX ± 0.10	.XXX° ±						